AMD Xilinx - XC2S50E-6PQG208C Datasheet

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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	384
Number of Logic Elements/Cells	1728
Total RAM Bits	32768
Number of I/O	146
Number of Gates	50000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2s50e-6pqg208c

Spartan-IIE Product Availability

Table 2 shows the maximum user I/Os available on the device and the number of user I/Os available for each device/package combination.

Table 2: **Spartan-IIE FPGA User I/O Chart**

Device	Maximum User I/O	Available User I/O According to Package Type				
		TQ144 TQG144	PQ208 PQG208	FT256 FTG256	FG456 FGG456	FG676 FGG676
XC2S50E	182	102	146	182	-	-
XC2S100E	202	102	146	182	202	-
XC2S150E	265	-	146	182	265	-
XC2S200E	289	-	146	182	289	-
XC2S300E	329	-	146	182	329	-
XC2S400E	410	-	-	182	329	410
XC2S600E	514	-	-	-	329	514

Notes:
1. User I/O counts include the four global clock/user input pins.

Configurable Logic Block

The basic building block of the Spartan-IIE FPGA CLB is the logic cell (LC). An LC includes a 4-input function generator, carry logic, and storage element. The output from the function generator in each LC drives the CLB output or the D input of the flip-flop. Each Spartan-IIE FPGA CLB contains four LCs, organized in two similar slices; a single slice is shown in Figure 6.

In addition to the four basic LCs, the Spartan-IIE FPGA CLB contains logic that combines function generators to provide functions of five or six inputs.

Look-Up Tables

Spartan-IIE FPGA function generators are implemented as 4-input look-up tables (LUTs). In addition to operating as a function generator, each LUT can provide a 16 x 1-bit synchronous RAM. Furthermore, the two LUTs within a slice can be combined to create a 16 x 2-bit or 32 x 1-bit synchronous RAM, or a 16 x 1-bit dual-port synchronous RAM.

The Spartan-IIE FPGA LUT can also provide a 16-bit shift register that is ideal for capturing high-speed or burst-mode data. This mode can also be used to store data in applications such as Digital Signal Processing.

Storage Elements

Storage elements in the Spartan-IIE FPGA slice can be configured either as edge-triggered D-type flip-flops or as level-sensitive latches. The D inputs can be driven either by function generators within the slice or directly from slice inputs, bypassing the function generators.

In addition to Clock and Clock Enable signals, each slice has synchronous set and reset signals (SR and BY). SR forces a storage element into the initialization state specified for it in the configuration. BY forces it into the opposite state. Alternatively, these signals may be configured to operate asynchronously.

All control signals are independently invertible, and are shared by the two flip-flops within the slice.

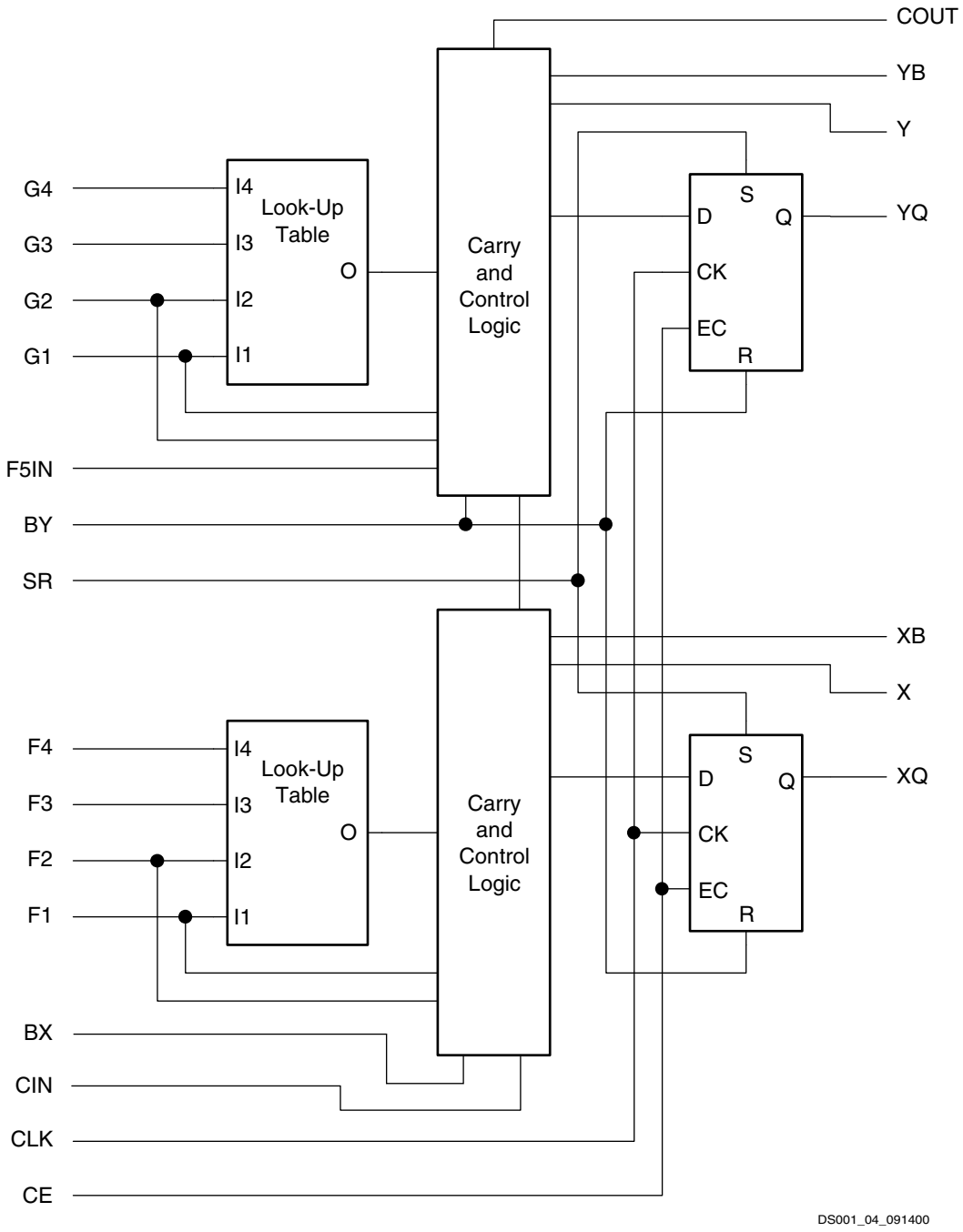

Figure 6: **Spartan-IIE CLB Slice** (two identical slices in each CLB)

Additional Logic

The F5 multiplexer in each slice combines the function generator outputs (Figure 7). This combination provides either a function generator that can implement any 5-input function, a 4:1 multiplexer, or selected functions of up to nine inputs.

Similarly, the F6 multiplexer combines the outputs of all four function generators in the CLB by selecting one of the two F5-multiplexer outputs. This permits the implementation of any 6-input function, an 8:1 multiplexer, or selected functions of up to 19 inputs.

Calculation of T_{IOOP} as a Function of Capacitance

T_{IOOP} is the propagation delay from the O Input of the IOB to the pad. The values for T_{IOOP} are based on the standard capacitive load (C_{SL}) for each I/O standard as listed in the table Constants for Calculating T_{IOOP}, below.

For other capacitive loads, use the formulas below to calculate an adjusted propagation delay, T_{IOOP1}.

$$T_{IOOP1} = T_{IOOP} + Adj + (C_{LOAD} - C_{SL}) * F_L$$

Where:

- Adj — is selected from IOB Output Delay Adjustments for Different Standards(1), page 40, according to the I/O standard used
- C_{LOAD} — is the capacitive load for the design
- F_L — is the capacitance scaling factor

Delay Measurement Methodology

Standard	V_L(1)	V_H(1)	Meas. Point	V_{REF} Typ(2)
LVTTL	0	3	1.4	-
LVCMOS2	0	2.5	1.125	-
PCI33_3	Per PCI Spec			-
PCI66_3	Per PCI Spec			-
GTL	V_{REF} – 0.2	V_{REF} + 0.2	V_{REF}	0.80
GTL+	V_{REF} – 0.2	V_{REF} + 0.2	V_{REF}	1.0
HSTL Class I	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.75
HSTL Class III	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.90
HSTL Class IV	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.90
SSTL3 I and II	V_{REF} – 1.0	V_{REF} + 1.0	V_{REF}	1.5
SSTL2 I and II	V_{REF} – 0.75	V_{REF} + 0.75	V_{REF}	1.25
CTT	V_{REF} – 0.2	V_{REF} + 0.2	V_{REF}	1.5
AGP	V_{REF} – (0.2xV_{CCO})	V_{REF} + (0.2xV_{CCO})	V_{REF}	Per AGP Spec
LVDS	1.2 – 0.125	1.2 + 0.125	1.2	
LVPECL	1.6 – 0.3	1.6 + 0.3	1.6	

Notes:

1. Input waveform switches between V_L and V_H.
2. Measurements are made at V_{REF} Typ, Maximum, and Minimum. Worst-case values are reported.
3. I/O parameter measurements are made with the capacitance values shown in the following table, Constants for Calculating T_{IOOP}. Refer to Application Note XAPP179 for appropriate terminations.
4. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

Constants for Calculating T_{IOOP}

Standard	C_{SL}(1) (pF)	F_L (ns/pF)
LVTTL Fast Slew Rate, 2 mA drive	35	0.41
LVTTL Fast Slew Rate, 4 mA drive	35	0.20
LVTTL Fast Slew Rate, 6 mA drive	35	0.13
LVTTL Fast Slew Rate, 8 mA drive	35	0.079
LVTTL Fast Slew Rate, 12 mA drive	35	0.044
LVTTL Fast Slew Rate, 16 mA drive	35	0.043
LVTTL Fast Slew Rate, 24 mA drive	35	0.033
LVTTL Slow Slew Rate, 2 mA drive	35	0.41
LVTTL Slow Slew Rate, 4 mA drive	35	0.20
LVTTL Slow Slew Rate, 6 mA drive	35	0.100
LVTTL Slow Slew Rate, 8 mA drive	35	0.086
LVTTL Slow Slew Rate, 12 mA drive	35	0.058
LVTTL Slow Slew Rate, 16 mA drive	35	0.050
LVTTL Slow Slew Rate, 24 mA drive	35	0.048
LVCMOS2	35	0.041
LVCMOS18	35	0.050
PCI 33 MHz 3.3V	10	0.050
PCI 66 MHz 3.3V	10	0.033
GTL	0	0.014
GTL+	0	0.017
HSTL Class I	20	0.022
HSTL Class III	20	0.016
HSTL Class IV	20	0.014
SSTL2 Class I	30	0.028
SSTL2 Class II	30	0.016
SSTL3 Class I	30	0.029
SSTL3 Class II	30	0.016
CTT	20	0.035
AGP	10	0.037

Notes:

1. I/O parameter measurements are made with the capacitance values shown above. Refer to Application Note XAPP179 for appropriate terminations.
2. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

CLB Distributed RAM Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
$T_{SHCKO16}$	Clock CLK to X/Y outputs (WE active, 16 x 1 mode)	0.6	1.5	0.6	1.7	ns
$T_{SHCKO32}$	Clock CLK to X/Y outputs (WE active, 32 x 1 mode)	0.8	1.9	0.8	2.1	ns
Setup/Hold Times with Respect to Clock CLK						
T_{AS} / T_{AH}	F/G address inputs	0.42 / 0	-	0.5 / 0	-	ns
T_{DS} / T_{DH}	BX/BY data inputs (DIN)	0.53 / 0	-	0.6 / 0	-	ns
T_{WS} / T_{WH}	CE input (WS)	0.7 / 0	-	0.8 / 0	-	ns
Clock CLK						
T_{WPH}	Pulse width, High	2.1	-	2.4	-	ns
T_{WPL}	Pulse width, Low	2.1	-	2.4	-	ns
T_{WC}	Clock period to meet address write cycle time	4.2	-	4.8	-	ns

CLB Shift Register Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T_{REG}	Clock CLK to X/Y outputs	1.2	2.9	1.2	3.2	ns
Setup/Hold Times with Respect to Clock CLK						
T_{SHDICK}	BX/BY data inputs (DIN)	0.53 / 0	-	0.6 / 0	-	ns
T_{SHCECK}	CE input (WS)	0.7 / 0	-	0.8 / 0	-	ns
Clock CLK						
T_{SRPH}	Pulse width, High	2.1	-	2.4	-	ns
T_{SRPL}	Pulse width, Low	2.1	-	2.4	-	ns

Block RAM Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T_{BCKO}	Clock CLK to DOUT output	0.6	3.1	0.6	3.5	ns
Setup/Hold Times with Respect to Clock CLK						
T_{BACK} / T_{BCKA}	ADDR inputs	1.0 / 0	-	1.1 / 0	-	ns
T_{BDCK}/ T_{BCKD}	DIN inputs	1.0 / 0	-	1.1 / 0	-	ns
T_{BECK}/ T_{BCKE}	EN inputs	2.2 / 0	-	2.5 / 0	-	ns
T_{BRCK}/ T_{BCKR}	RST input	2.1 / 0	-	2.3 / 0	-	ns
T_{BWCK}/ T_{BCKW}	WEN input	2.0 / 0	-	2.2 / 0	-	ns
Clock CLK						
T_{BPWH}	Pulse width, High	1.4	-	1.5	-	ns
T_{BPWL}	Pulse width, Low	1.4	-	1.5	-	ns
T_{BCCS}	CLKA -> CLKB setup time for different ports	2.7	-	3.0	-	ns

Spartan-IIE Package Pinouts

The Spartan®-IIE family of FPGAs is available in five popular, low-cost packages, including plastic quad flat packs and fine-pitch ball grid arrays. Family members have footprint compatibility across devices provided in the same package, with minor exceptions due to the smaller number of I/O in smaller devices or due to LVDS/LVPECL pin pairing. The Spartan-IIE family is not footprint compatible with any other FPGA family. The following package-specific pinout tables indicate function, pin, and bank information for all devices available in that package. The pinouts follow the pad locations around the die, starting from pin 1 on the QFP packages.

Table 12: **Spartan-IIE Family Package Options**

Package	Leads	Type	Maximum I/O	Lead Pitch (mm)	Footprint Area (mm)	Height (mm)	Mass[1] (g)
TQ144 / TQG144	144	Thin Quad Flat Pack (TQFP)	102	0.5	22 x 22	1.60	1.4
PQ208 / PQG208	208	Plastic Quad Flat Pack (PQFP)	146	0.5	30.6 x 30.6	3.70	5.3
FT256 / FTG256	256	Fine-pitch Thin Ball Grid Array (FBGA)	182	1.0	17 x 17	1.55	1.0
FG456 / FGG456	456	Fine-pitch Ball Grid Array (FBGA)	329	1.0	23 x 23	2.60	2.2
FG676 / FGG676	676	Fine-pitch Ball Grid Array (FBGA)	514	1.0	27 x 27	2.60	3.1

Notes:

1. Package mass is ±10%.

Package Overview

Table 12 shows the five low-cost, space-saving production package styles for the Spartan-IIE family.

Each package style is available in an environmentally friendly lead-free (Pb-free) option. The Pb-free packages include an extra ‘G’ in the package style name. For example, the standard “TQ144” package becomes “TQG144” when ordered as the Pb-free option. Leaded (non-Pb-free) packages may be available for selected devices, with the same pin-out and without the "G" in the ordering code; contact Xilinx® sales for more information. The mechanical dimensions of the standard and Pb-free packages are similar, as shown in the mechanical drawings provided in Table 13.

For additional package information, see UG112: *Device Package User Guide*.

Mechanical Drawings

Detailed mechanical drawings for each package type are available from the Xilinx web site at the specified location in Table 13.

Material Declaration Data Sheets (MDDS) are also available on the Xilinx web site for each package.

Table 13: **Xilinx Package Documentation**

Package	Drawing	MDDS
TQ144	Package Drawing	PK169_TQ144
TQG144		PK126_TQG144
PQ208	Package Drawing	PK166_PQ208
PQG208		PK123_PQG208
FT256	Package Drawing	PK158_FT256
FTG256		PK115_FTG256
FG456	Package Drawing	PK154_FG456
FGG456		PK109_FGG456
FG676	Package Drawing	PK155_FG676
FGG676		PK111_FGG676

Low Voltage Differential Signals (LVDS and LVPECL)

The Spartan-IIE family features low-voltage differential signaling (LVDS and LVPECL). Each signal utilizes two pins on the Spartan-IIE device, known as differential pin pairs. Each differential pin pair has a Positive (P) and a Negative (N) pin. These pairs are labeled in the following manner.

I/O, L#[P/N][-/_Y/_YY]

where

L = LVDS or LVPECL pin

= Pin pair number

P = Positive

N = Negative

_Y = Asynchronous output allowed (device-dependent)

_YY = Asynchronous output allowed (all devices)

Available Differential Pairs According to Package Type

Device	TQ144	PQ208	FT256	FG456	FG676
XC2S50E	28	50	83	-	-
XC2S100E	28	50	83	86	-
XC2S150E	-	50	83	114	-
XC2S200E	-	50	83	120	-
XC2S300E	-	50	83	120	-
XC2S400E	-	-	83	120	172
XC2S600E	-	-	-	120	205

Synchronous or Asynchronous

I/O pins for differential signals can either be synchronous or asynchronous, input or output. Differential signaling requires the pins of each pair to switch simultaneously. If the output signals driving the pins are from IOB flip-flops, they are synchronous. If the signals driving the pins are from internal logic, they are asynchronous, and therefore more care must be taken that they are simultaneous. Any differential pairs can be used for synchronous input and output signals as well as asynchronous input signals.

However, only the differential pairs with the _Y or _YY suffix can be used for asynchronous output signals.

Asynchronous Output Pad Name Designation

Because of differences between densities, the differential pairs that can be used for asynchronous outputs vary by device. The pairs that are available in all densities for a given package have the _YY suffix. These pins should be used for differential asynchronous outputs if the design may later move to a different density. All other differential pairs that can be used for asynchronous outputs have the _Y suffix.

To simplify the following tables, the "Pad Name" column shows the part of the name that is common across densities. The "Pad Name" column leaves out the _Y suffix and the "LVDS Asynchronous Output Option" column indicates the densities that allow asynchronous outputs for LVDS or LVPECL on the given pin.

DLL Pins

Pins labeled "I/O (DLL)" can be used as general-purpose I/O or as inputs to the DLL. Adjacent DLL pins form a differential pair. They reside in two different banks, so if they are outputs the V_{CCO} level must be the same for both banks. Each DLL pin can also be paired with the adjacent GCK clock pin for a differential clock input. The "I/O (DLL)" pin always becomes the N terminal when paired with GCK, even if it is labeled "P" for its pairing with the adjacent DLL pin.

VREF Pins

Pins labeled "I/O, VREF" can be used as either an I/O or a VREF pin. If any I/O pin within the bank requires a VREF input, all the VREF pins in the bank must be connected to the same voltage. See the I/O banking rules in the Functional Description module for more detail. If no pin in a given bank requires VREF, then that bank's VREF pins can be used as general I/O.

To simplify the following tables, the "Pad Name" column shows the part of the name that is common across densities. When VREF is only available in limited densities, the "Pad Name" column leaves out the VREF designation and the "VREF Option" column indicates the densities that provide VREF on the given pin.

VCCO Banks

In the TQ144 and PQ208 packages, the eight banks have VCCO connected together. Thus, only one VCCO is allowed in these packages, although different VREF values are allowed in each of the eight banks. See I/O Banking.

PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)

Pad Name		Pin	LVDS Async. Output Option	V_{REF} Option
Function	Bank			
I/O, VREF Bank 6, L39P	6	P45	XC2S100E, 150E	All
I/O, L39N	6	P46	XC2S100E, 150E	-
I/O	6	P47	-	XC2S200E, 300E
I/O, L38P_YY	6	P48	All	-
I/O, L38N_YY	6	P49	All	-
M1	-	P50	-	-
GND	-	P51	-	-
M0	-	P52	-	-
VCCO	-	P53	-	-
M2	-	P54	-	-
I/O, L37N_YY	5	P55	All	-
I/O, L37P_YY	5	P56	All	-
I/O	5	P57	-	XC2S200E, 300E
I/O	5	P58	-	-
I/O, VREF Bank 5, L36N_YY	5	P59	All	All
I/O, L36P_YY	5	P60	All	-
I/O, L35N	5	P61	XC2S50E, 100E, 300E	-
I/O, L35P	5	P62	XC2S50E, 100E, 300E	-
I/O, L34N	5	P63	XC2S50E, 100E, 200E, 300E	XC2S100E, 150E, 200E, 300E
I/O, L34P	5	P64	XC2S50E, 100E, 200E, 300E	-
GND	-	P65	-	-

PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)

Pad Name		Pin	LVDS Async. Output Option	V_{REF} Option
Function	Bank			
VCCO	-	P66	-	-
VCCINT	-	P67	-	-
I/O, L33N	5	P68	XC2S50E, 100E, 200E, 300E	-
I/O, L33P	5	P69	XC2S50E, 100E, 200E, 300E	-
I/O	5	P70	-	-
I/O, L32N	5	P71	XC2S100E, 150E	-
GND	-	P72	-	-
I/O, VREF Bank 5, L32P	5	P73	XC2S100E, 150E	All
I/O	5	P74	-	-
I/O (DLL), L31N	5	P75	-	-
VCCINT	-	P76	-	-
GCK1, I	5	P77	-	-
VCCO	-	P78	-	-
GND	-	P79	-	-
GCK0, I	4	P80	-	-
I/O (DLL), L31P	4	P81	-	-
I/O	4	P82	-	-
I/O, L30N	4	P83	XC2S50E, 200E, 300E	-
I/O, VREF Bank 4, L30P	4	P84	XC2S50E, 200E, 300E	All
GND	-	P85	-	-
I/O, L29N	4	P86	XC2S50E, 200E, 300E	-
I/O, L29P	4	P87	XC2S50E, 200E, 300E	-
I/O, L28N	4	P88	XC2S50E, 100E, 200E, 300E	-

PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)

Pad Name		Pin	LVDS Async. Output Option	V_{REF} Option
Function	Bank			
I/O, VREF Bank 1, L6P	1	P178	XC2S50E, 200E, 300E	All
I/O, L6N	1	P179	XC2S50E, 200E, 300E	-
I/O	1	P180	-	-
I/O (DLL), L5P	1	P181	-	-
GCK2, I	1	P182	-	-
GND	-	P183	-	-
VCCO	-	P184	-	-
GCK3, I	0	P185	-	-
VCCINT	-	P186	-	-
I/O (DLL), L5N	0	P187	-	-
I/O, L4P	0	P188	XC2S50E, 200E, 300E	-
I/O, VREF Bank 0, L4N	0	P189	XC2S50E, 200E, 300E	All
GND	-	P190	-	-
I/O, L3P	0	P191	XC2S50E, 200E, 300E	-
I/O, L3N	0	P192	XC2S50E, 200E, 300E	-
I/O, L2P	0	P193	XC2S50E, 100E, 200E, 300E	-
I/O, L2N	0	P194	XC2S50E, 100E, 200E, 300E	-
VCCINT	-	P195	-	-
VCCO	-	P196	-	-
GND	-	P197	-	-
I/O, L1P	0	P198	XC2S50E, 100E, 200E, 300E	-
I/O, L1N	0	P199	XC2S50E, 100E, 200E, 300E	XC2S100E, 150E, 200E, 300E
I/O	0	P200	-	-

PQ208 Pinouts (XC2S50E, XC2S100E, XC2S150E, XC2S200E, XC2S300E)

Pad Name		Pin	LVDS Async. Output Option	V_{REF} Option
Function	Bank			
I/O	0	P201	-	-
I/O, L0P_YY	0	P202	All	-
I/O, VREF Bank 0, L0N_YY	0	P203	All	All
I/O	0	P204	-	-
I/O	0	P205	-	XC2S200E, 300E
I/O	0	P206	-	-
TCK	-	P207	-	-
VCCO	-	P208	-	-

PQ208 Differential Clock Pins

Clock	Bank	P		N	
		Pin	Name	Pin	Name
GCK0	4	P80	GCK0, I	P81	I/O (DLL), L31P
GCK1	5	P77	GCK1, I	P75	I/O (DLL), L31N
GCK2	1	P182	GCK2, I	P181	I/O (DLL), L5P
GCK3	0	P185	GCK3, I	P187	I/O (DLL), L5N

FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)

Pad Name		Pin	LVDS Async. Output Option	V_{REF} Option	Device-Specific Pinouts: XC2S					
Function	Bank				100E	150E	200E	300E	400E	600E
GCK0, I	4	AA12	-	-	GCK0, I	GCK0, I	GCK0, I	GCK0, I	GCK0, I	GCK0, I
I/O (DLL), L#P	4	Y12	-	-	I/O (DLL), L53P	I/O (DLL), L70P	I/O (DLL), L75P	I/O (DLL), L75P	I/O (DLL), L75P	I/O (DLL), L75P
I/O	4	W12	-	-	-	-	-	I/O	I/O	I/O
I/O, L#N	4	V12	XC2S150E, 300E, 600E	-	-	I/O, L69N_Y	I/O, L74N	I/O, L74N_Y	I/O, L74N	I/O, L74N_Y
I/O, L#P	4	U12	XC2S150E, 300E, 600E	XC2S400E, 600E	I/O, L52N	I/O, L69P_Y	I/O, L74P	I/O, L74P_Y	I/O, VREF Bank 4, L74P	I/O, VREF Bank 4, L74P_Y
I/O, L#N	4	AB13	XC2S300E, 600E	-	I/O, L52P	I/O	I/O, L73N	I/O, L73N_Y	I/O, L73N	I/O, L73N_Y
I/O, L#P	4	AA13	XC2S300E, 600E	-	-	-	I/O, L73P	I/O, L73P_Y	I/O, L73P	I/O, L73P_Y
I/O	4	Y13	-	-	-	-	-	I/O	I/O	I/O
I/O, L#N	4	W13	XC2S200E, 300E, 400E, 600E	-	I/O, L51N	I/O, L68N	I/O, L72N_Y	I/O, L72N_Y	I/O, L72N_Y	I/O, L72N_Y
I/O, VREF Bank 4, L#P	4	V13	XC2S200E, 300E, 400E, 600E	All	I/O, VREF Bank 4, L51P	I/O, VREF Bank 4, L68P	I/O, VREF Bank 4, L72P_Y	I/O, VREF Bank 4, L72P_Y	I/O, VREF Bank 4, L72P_Y	I/O, VREF Bank 4, L72P_Y
I/O	4	U13	-	-	I/O, L50N	I/O, L67N	I/O	I/O	I/O	I/O
I/O, L#N	4	AB14	-	-	I/O, L50P	I/O, L67P	I/O, L71N	I/O, L71N	I/O, L71N	I/O, L71N
I/O, L#P	4	AA14	-	-	-	-	I/O, L71P	I/O, L71P	I/O, L71P	I/O, L71P
I/O	4	AB15	-	-	-	-	I/O	I/O	I/O	I/O
I/O, L#N	4	Y14	XC2S100E, 150E, 200E	-	I/O, L49N_Y	I/O, L66N_Y	I/O, L70N_Y	I/O, L70N	I/O, L70N	I/O, L70N
I/O, L#P	4	W14	XC2S100E, 150E, 200E	-	I/O, L49P_Y	I/O, L66P_Y	I/O, L70P_Y	I/O, L70P	I/O, L70P	I/O, L70P
I/O, L#N	4	U14	XC2S150E, 200E	-	-	I/O, L65N_Y	I/O, L69N_Y	I/O, L69N	I/O, L69N	I/O, L69N
I/O, L#P	4	V14	XC2S150E, 200E	-	-	I/O, L65P_Y	I/O, L69P_Y	I/O, L69P	I/O, L69P	I/O, L69P
I/O, L#N	4	AA15	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L48N_Y	I/O, L64N	I/O, L68N_Y	I/O, L68N_Y	I/O, L68N_Y	I/O, L68N_Y
I/O, L#P	4	Y15	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L48P_Y	I/O, L64P	I/O, L68P_Y	I/O, L68P_Y	I/O, L68P_Y	I/O, L68P_Y
I/O, L#N	4	W15	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L47N_Y	I/O, L63N	I/O, L67N_Y	I/O, L67N_Y	I/O, L67N_Y	I/O, L67N_Y
I/O, VREF Bank 4, L#P	4	V15	XC2S100E, 200E, 300E, 400E, 600E	All	I/O, VREF Bank 4, L47P_Y	I/O, VREF Bank 4, L63P	I/O, VREF Bank 4, L67P_Y	I/O, VREF Bank 4, L67P_Y	I/O, VREF Bank 4, L67P_Y	I/O, VREF Bank 4, L67P_Y
I/O	4	AB16	-	-	-	-	-	I/O	I/O	I/O
I/O	4	AB17	-	-	I/O	I/O	I/O	I/O	I/O	I/O

FG456 Pinouts (XC2S100E, XC2S150E, XC2S200E, XC2S300E, XC2S400E, XC2S600E)

Pad Name			LVDS Async. Output Option	V_{REF} Option	Device-Specific Pinouts: XC2S					
Function	Bank	Pin			100E	150E	200E	300E	400E	600E
I/O, L#P_YY	0	A6	All	-	I/O, L2P_YY	I/O, L3P_YY	I/O, L3P_YY	I/O, L3P_YY	I/O, L3P_YY	I/O, L3P_YY
I/O, VREF Bank 0, L#N_YY	0	B6	All	All	I/O, VREF Bank 0, L2N_YY	I/O, VREF Bank 0, L3N_YY	I/O, VREF Bank 0, L3N_YY	I/O, VREF Bank 0, L3N_YY	I/O, VREF Bank 0, L3N_YY	I/O, VREF Bank 0, L3N_YY
I/O	0	C6	XC2S100E	-	I/O, L1P_Y	I/O	I/O	I/O	I/O	I/O
I/O, L#P	0	A5	XC2S100E	-	I/O, L1N_Y	I/O, L2P	I/O, L2P	I/O, L2P	I/O, L2P	I/O, L2P
I/O, L#N	0	B5	-	-	-	I/O, L2N	I/O, L2N	I/O, L2N	I/O, L2N	I/O, L2N
I/O	0	D6	-	-	-	-	-	I/O	I/O	I/O
I/O, L#P	0	B4	XC2S100E, 200E, 300E, 400E, 600E	-	I/O, L0P_Y	I/O, L1P	I/O, L1P_Y	I/O, L1P_Y	I/O, L1P_Y	I/O, L1P_Y
I/O, L#N	0	C5	XC2S100E, 200E, 300E, 400E, 600E	XC2S200E, 300E, 400E, 600E	I/O, L0N_Y	I/O, L1N	I/O, VREF Bank 0, L1N_Y	I/O, VREF Bank 0, L1N_Y	I/O, VREF Bank 0, L1N_Y	I/O, VREF Bank 0, L1N_Y
I/O	0	A4	-	-	I/O	I/O	I/O	I/O	I/O	I/O
I/O, L#P	0	A3	XC2S150E, 400E, 600E	-	-	I/O, L0P_Y	I/O, L0P	I/O, L0P	I/O, L0P_Y	I/O, L0P_Y
I/O, L#N	0	B3	XC2S150E, 400E, 600E	-	-	I/O, L0N_Y	I/O, L0N	I/O, L0N	I/O, L0N_Y	I/O, L0N_Y
I/O	0	C4	-	-	-	-	-	I/O	I/O	I/O
I/O	0	D5	-	-	I/O	I/O	I/O	I/O	I/O	I/O
TCK	-	E6	-	-	TCK	TCK	TCK	TCK	TCK	TCK

Notes:
1. Although designated with the _YY suffix in the XC2S100E, XC2S150E, XC2S200E, and XC2S300E, these differential pairs are not asynchronous in the XC2S400E.

FG456 Differential Clock Pins

Clock	Bank	P		N	
		Pin	Name	Pin	Name
GCK0	4	AA12	GCK0, I	Y12	I/O (DLL), L#P
GCK1	5	AB12	GCK1, I	AB11	I/O (DLL), L#N
GCK2	1	A11	GCK2, I	A12	I/O (DLL), L#P
GCK3	0	C11	GCK3, I	B11	I/O (DLL), L#N

Additional FG456 Package Pins

VCCINT Pins								
D4(1)	D19(1)	E5	E18	F6	F17	G7	G8	G15
G16	H7	H16	R7	R16	T7	T8	T15	T16
U6	U17	V5	V18	W4(1)	W19(1)	-	-	-
VCCO Bank 0 Pins								
F7	F8	G9	G10	-	-	-	-	-

FG676 Pinouts (XC2S400E, XC2S600E) *(Continued)*

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O, L201P	7	E4	XC2S400E	-	I/O, L201P_Y	I/O, L201P
I/O, L201N	7	F5	XC2S400E	-	I/O, L201N_Y	I/O, L201N
I/O, VREF Bank 7, L200P	7	F4	XC2S600E	All	I/O, VREF Bank 7, L200P	I/O, VREF Bank 7, L200P_Y
I/O, L200N	7	F3	XC2S600E	-	I/O, L200N	I/O, L200N_Y
I/O, L199P	7	F2	XC2S600E	-	-	I/O, L199P_Y
I/O, L199N	7	F1	XC2S600E	-	I/O	I/O, L199N_Y
I/O, L198P	7	G6	XC2S400E	-	I/O, L198P_Y	I/O, L198P
I/O, L198N	7	G5	XC2S400E	-	I/O, L198N_Y	I/O, L198N
I/O, L197P	7	G4	XC2S600E	-	I/O, L197P	I/O, L197P_Y
I/O, L197N	7	G3	XC2S600E	-	I/O, L197N	I/O, L197N_Y
I/O, VREF Bank 7, L196P_YY	7	G2	All	All	I/O, VREF Bank 7, L196P_YY	I/O, VREF Bank 7, L196P_YY
I/O, L196N_YY	7	G1	All	-	I/O, L196N_YY	I/O, L196N_YY
I/O	7	H7	-	-	I/O	I/O
I/O, L195P_YY	7	H6	All	-	I/O, L195P_YY	I/O, L195P_YY
I/O, L195N_YY	7	H5	All	-	I/O, L195N_YY	I/O, L195N_YY
I/O	7	J8	-	-	-	I/O
I/O, L194P	7	H2	XC2S400E	-	I/O, L194P_Y	I/O, L194P
I/O, L194N	7	H1	XC2S400E	-	I/O, L194N_Y	I/O, L194N
I/O, L193P	7	J7	XC2S600E	XC2S600E	I/O	I/O, VREF Bank 7, L193P_Y
I/O, L193N	7	J6	XC2S600E	-	-	I/O, L193N_Y
I/O	7	J5	-	-	I/O	I/O
I/O, L192P_YY	7	J4	All	-	I/O, L192P_YY	I/O, L192P_YY
I/O, L192N_YY	7	J3	All	-	I/O, L192N_YY	I/O, L192N_YY
I/O	7	K5	-	-	I/O	I/O
I/O, VREF Bank 7, L191P_YY	7	J2	All	All	I/O, VREF Bank 7, L191P_YY	I/O, VREF Bank 7, L191P_YY
I/O, L191N_YY	7	J1	All	-	I/O, L191N_YY	I/O, L191N_YY
I/O, L190P_YY	7	K8	All	-	I/O, L190P_YY	I/O, L190P_YY
I/O, L190N_YY	7	K7	All	-	I/O, L190N_YY	I/O, L190N_YY
I/O	7	K4	-	-	-	I/O
I/O, L189P_YY	7	K3	All	-	I/O, L189P_YY	I/O, L189P_YY
I/O, L189N_YY	7	K2	All	-	I/O, L189N_YY	I/O, L189N_YY
I/O	7	K1	-	-	-	I/O

FG676 Pinouts (XC2S400E, XC2S600E) *(Continued)*

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O, L164N	6	W2	XC2S600E	XC2S600E	I/O, L164N	I/O, VREF Bank 6, L164N_Y
I/O, L163P	6	W5	XC2S400E	-	I/O, L163P_Y	I/O, L163P
I/O, L163N	6	W6	XC2S400E	-	I/O, L163N_Y	I/O, L163N
I/O	6	W7	-	-	I/O	I/O
I/O, L162P_YY	6	Y1	All	-	I/O, L162P_YY	I/O, L162P_YY
I/O, L162N_YY	6	Y2	All	-	I/O, L162N_YY	I/O, L162N_YY
I/O	6	Y3	-	-	-	I/O
I/O, L161P_YY	6	Y4	All	-	I/O, L161P_YY	I/O, L161P_YY
I/O, VREF Bank 6, L161N_YY	6	Y5	All	All	I/O, VREF Bank 6, L161N_YY	I/O, VREF Bank 6, L161N_YY
I/O	6	Y6	-	-	I/O	I/O
I/O, L160P_YY	6	AA1	All	-	I/O, L160P_YY	I/O, L160P_YY
I/O, L160N_YY	6	AA2	All	-	I/O, L160N_YY	I/O, L160N_YY
I/O, L159P	6	AA3	XC2S600E	-	I/O, L159P	I/O, L159P_Y
I/O, L159N	6	AA4	XC2S600E	-	I/O, L159N	I/O, L159N_Y
I/O	6	Y7	-	-	-	I/O
I/O, L158P	6	AA5	XC2S600E	-	I/O, L158P	I/O, L158P_Y
I/O, VREF Bank 6, L158N	6	AB5	XC2S600E	All	I/O, VREF Bank 6, L158N	I/O, VREF Bank 6, L158N_Y
I/O, L157P	6	AB1	XC2S400E	-	I/O, L157P_Y	I/O, L157P
I/O, L157N	6	AB2	XC2S400E	-	I/O, L157N_Y	I/O, L157N
I/O, L156P	6	AC1	XC2S600E	-	-	I/O, L156P_Y
I/O, L156N	6	AC2	XC2S600E	-	I/O	I/O, L156N_Y
I/O, L155P_YY	6	AC3	All	-	I/O, L155P_YY	I/O, L155P_YY
I/O, L155N_YY	6	AB4	All	-	I/O, L155N_YY	I/O, L155N_YY
I/O, L154P	6	AD1	-	-	-	I/O, L154P
I/O, L154N	6	AD2	-	-	-	I/O, L154N
I/O, L153P_YY	6	AE1	All	-	I/O, L153P_YY	I/O, L153P_YY
I/O, L153N_YY	6	AF2	All	-	I/O, L153N_YY	I/O, L153N_YY
M1	-	AE3	-	-	M1	M1
M0	-	AF3	-	-	M0	M0
M2	-	AD4	-	-	M2	M2

FG676 Pinouts (XC2S400E, XC2S600E) *(Continued)*

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O	5	AC5	-	-	I/O	I/O
I/O, L152N	5	AE4	-	-	I/O	I/O, L152N
I/O, L152P	5	AF4	-	-	-	I/O, L152P
I/O, L151N	5	AE5	-	-	-	I/O, L151N
I/O, L151P	5	AF5	-	-	I/O	I/O, L151P
I/O, L150N	5	AA6	XC2S400E	-	I/O, L150N_Y	I/O, L150N
I/O, L150P	5	AB6	XC2S400E	-	I/O, L150P_Y	I/O, L150P
I/O, L149N_YY	5	AC6	All	-	I/O, L149N_YY	I/O, L149N_YY
I/O, L149P_YY	5	AD6	All	-	I/O, L149P_YY	I/O, L149P_YY
I/O, VREF Bank 5, L148N_YY	5	AE6	All	All	I/O, VREF Bank 5, L148N_YY	I/O, VREF Bank 5, L148N_YY
I/O, L148P_YY	5	AF6	All	-	I/O, L148P_YY	I/O, L148P_YY
I/O, L147N	5	AA7	XC2S600E	-	-	I/O, L147N_Y
I/O, L147P	5	AB7	XC2S600E	-	I/O	I/O, L147P_Y
I/O, L146N_YY	5	AC7	All	-	I/O, L146N_YY	I/O, L146N_YY
I/O, L146P_YY	5	AD7	All	-	I/O, L146P_YY	I/O, L146P_YY
I/O, L145N_YY	5	AE7	All	-	I/O, L145N_YY	I/O, L145N_YY
I/O, L145P_YY	5	AF7	All	-	I/O, L145P_YY	I/O, L145P_YY
I/O, VREF Bank 5, L144N_YY	5	Y8	All	All	I/O, VREF Bank 5, L144N_YY	I/O, VREF Bank 5, L144N_YY
I/O, L144P_YY	5	AA8	All	-	I/O, L144P_YY	I/O, L144P_YY
I/O, L143N_YY	5	AE8	All	-	I/O, L143N_YY	I/O, L143N_YY
I/O, L143P_YY	5	AF8	All	-	I/O, L143P_YY	I/O, L143P_YY
I/O	5	AB8	-	-	I/O	I/O
I/O, L142N	5	W9	XC2S600E	-	I/O, L142N	I/O, L142N_Y
I/O, L142P	5	Y9	XC2S600E	-	I/O, L142P	I/O, L142P_Y
I/O, L141N	5	AA9	XC2S600E	XC2S600E	-	I/O, VREF Bank 5, L141N_Y
I/O, L141P	5	AB9	XC2S600E	-	I/O	I/O, L141P_Y
I/O, L140N_YY	5	AC9	All	-	I/O, L140N_YY	I/O, L140N_YY
I/O, L140P_YY	5	AD9	All	-	I/O, L140P_YY	I/O, L140P_YY
I/O, L139N_YY	5	AE9	All	-	I/O, L139N_YY	I/O, L139N_YY
I/O, L139P_YY	5	AF9	All	-	I/O, L139P_YY	I/O, L139P_YY
I/O, VREF Bank 5, L138N_YY	5	W10	All	All	I/O, VREF Bank 5, L138N_YY	I/O, VREF Bank 5, L138N_YY

FG676 Pinouts (XC2S400E, XC2S600E) *(Continued)*

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O	3	N18	-	-	-	I/O
I/O (TRDY)	3	N24	-	-	I/O (TRDY)	I/O (TRDY)
I/O (IRDY), L75N_YY	2	N26	All	-	I/O (IRDY), L75N_YY	I/O (IRDY), L75N_YY
I/O, L75P_YY	2	N25	All	-	I/O, L75P_YY	I/O, L75P_YY
I/O	2	N19	-	-	-	I/O
I/O, L74N	2	N23	XC2S600E	-	-	I/O, L74N_Y
I/O, L74P	2	N22	XC2S600E	-	I/O	I/O, L74P_Y
I/O	2	M23	-	-	I/O	I/O
I/O, L73N	2	N21	XC2S600E	-	I/O, L73N	I/O, L73N_Y
I/O, VREF Bank 2, L73P	2	N20	XC2S600E	All	I/O, VREF Bank 2, L73P	I/O, VREF Bank 2, L73P_Y
I/O, L72N	2	M26	XC2S400E	-	I/O, L72N_Y	I/O, L72N
I/O, L72P	2	M25	XC2S400E	-	I/O, L72P_Y	I/O, L72P
I/O	2	M22	-	-	-	I/O
I/O, L71N_YY	2	M21	All	-	I/O, L71N_YY	I/O, L71N_YY
I/O, L71P_YY	2	M20	All	-	I/O, L71P_YY	I/O, L71P_YY
I/O	2	L26	-	-	-	I/O
I/O (D3), L70N_YY	2	M19	All	-	I/O (D3), L70N_YY	I/O (D3), L70N_YY
I/O, VREF Bank 2, L70P_YY	2	M18	All	All	I/O, VREF Bank 2, L70P_YY	I/O, VREF Bank 2, L70P_YY
I/O, L69N	2	L25	XC2S600E	-	I/O, L69N	I/O, L69N_Y
I/O, L69P	2	L24	XC2S600E	-	I/O, L69P	I/O, L69P_Y
I/O	2	L22	-	-	-	I/O
I/O, L68N	2	L21	XC2S600E	-	I/O, L68N	I/O, L68N_Y
I/O, L68P	2	L20	XC2S600E	-	I/O, L68P	I/O, L68P_Y
I/O	2	L19	-	-	-	I/O
I/O, L67N	2	K26	XC2S600E	-	I/O, L67N	I/O, L67N_Y
I/O, L67P	2	K25	XC2S600E	-	I/O, L67P	I/O, L67P_Y
I/O, L66N	2	K24	-	-	-	I/O, L66N
I/O, L66P	2	K23	-	-	I/O	I/O, L66P
I/O	2	K22	-	-	-	I/O
I/O, L65N	2	K20	XC2S600E	-	I/O	I/O, L65N_Y
I/O, L65P	2	K19	XC2S600E	-	I/O	I/O, L65P_Y
I/O	2	J26	-	-	I/O	I/O

FG676 Pinouts (XC2S400E, XC2S600E) *(Continued)*

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O, VREF Bank 1, L25P	1	D14	XC2S600E	All	I/O, VREF Bank 1, L25P	I/O, VREF Bank 1, L25P_Y
I/O, L25N	1	C14	XC2S600E	-	I/O, L25N	I/O, L25N_Y
I/O	1	J13	-	-	-	I/O
I/O, L24P	1	C13	-	-	I/O, L24P	I/O, L24P
I/O, L24N	1	D13	-	-	I/O, L24N	I/O, L24N
I/O	1	H13	-	-	-	I/O
I/O (DLL), L23P	1	B14	-	-	I/O (DLL), L23P	I/O (DLL), L23P
GCK2, I	1	A14	-	-	GCK2, I	GCK2, I
GCK3, I	0	A13	-	-	GCK3, I	GCK3, I
I/O (DLL), L23N	0	B13	-	-	I/O (DLL), L23N	I/O (DLL), L23N
I/O	0	E13	-	-	-	I/O
I/O, L22P_YY	0	F13	All	-	I/O, L22P_YY	I/O, L22P_YY
I/O, L22N_YY	0	G13	All	-	I/O, L22N_YY	I/O, L22N_YY
I/O, L21P	0	A12	XC2S600E	-	-	I/O, L21P_Y
I/O, VREF Bank 0, L21N	0	B12	XC2S600E	All	I/O, VREF Bank 0	I/O, VREF Bank 0, L21N_Y
I/O, L20P	0	D12	XC2S600E	-	I/O, L20P	I/O, L20P_Y
I/O, L20N	0	E12	XC2S600E	-	I/O, L20N	I/O, L20N_Y
I/O	0	F12	-	-	-	I/O
I/O, L19P_YY	0	G12	All	-	I/O, L19P_YY	I/O, L19P_YY
I/O, L19N_YY	0	H12	All	-	I/O, L19N_YY	I/O, L19N_YY
I/O	0	J12	-	-	-	I/O
I/O, L18P_YY	0	A11	All	-	I/O, L18P_YY	I/O, L18P_YY
I/O, VREF Bank 0, L18N_YY	0	B11	All	All	I/O, VREF Bank 0, L18N_YY	I/O, VREF Bank 0, L18N_YY
I/O, L17P_YY	0	E11	All	-	I/O, L17P_YY	I/O, L17P_YY
I/O, L17N_YY	0	F11	All	-	I/O, L17N_YY	I/O, L17N_YY
I/O	0	C11	-	-	-	I/O
I/O, L16P	0	G11	-	-	I/O, L16P	I/O, L16P
I/O, L16N	0	H11	-	-	I/O, L16N	I/O, L16N
I/O	0	C10	-	-	-	I/O
I/O, L15P_YY	0	A10	All	-	I/O, L15P_YY	I/O, L15P_YY
I/O, L15N_YY	0	B10	All	-	I/O, L15N_YY	I/O, L15N_YY
I/O, L14P_YY	0	D10	All	-	I/O, L14P_YY	I/O, L14P_YY

FG676 Pinouts (XC2S400E, XC2S600E) *(Continued)*

Pad Name		Pin	LVDS Async. Output Option	VREF Option	Device-Specific Pinouts	
Function	Bank				XC2S400E	XC2S600E
I/O, L2N_YY	0	E5	All	-	I/O, L2N_YY	I/O, L2N_YY
I/O, L1P_YY	0	B4	All	-	I/O, L1P_YY	I/O, L1P_YY
I/O, L1N_YY	0	C4	All	-	I/O, L1N_YY	I/O, L1N_YY
I/O, L0P	0	A3	XC2S600E	-	I/O	I/O, L0P_Y
I/O, L0N	0	B3	XC2S600E	-	-	I/O, L0N_Y
I/O	0	A4	-	-	I/O	I/O
TCK	-	A2	-	-	TCK	TCK

FG676 Differential Clock Pins

Clock	Bank	P Input		N Input	
		Pin	Name	Pin	Name
GCK0	4	AF14	GCK0, I	AE14	I/O (DLL), L126P
GCK1	5	AF13	GCK1, I	AE13	I/O (DLL), L126N
GCK2	1	A14	GCK2, I	B14	I/O (DLL), L23P
GCK3	0	A13	GCK3, I	B13	I/O (DLL), L23N

Additional FG676 Package Pins

VCCINT Pins						
H8	H19	J9	J18	K10	K11	K16
K17	L10	L17	T10	T17	U10	U11
U16	U17	V9	V18	W8	W19	-
VCCO Bank 0 Pins						
C5	C8	D11	J10	J11	K12	K13
VCCO Bank 1 Pins						
C19	C22	D16	J16	J17	K14	K15
VCCO Bank 2 Pins						
E24	H24	K18	L18	L23	M17	N17
VCCO Bank 3 Pins						
P17	R17	T18	T23	U18	W24	AB24
VCCO Bank 4 Pins						
U14	U15	V16	V17	AC16	AD19	AD22
VCCO Bank 5 Pins						
U12	U13	V10	V11	AC11	AD5	AD8
VCCO Bank 6 Pins						
P10	R10	T4	T9	U9	W3	AB3
VCCO Bank 7 Pins						
H3	K9	L4	L9	M10	N10	E3

Revision History

Date	Version	Description
11/15/2001	1.0	Initial Xilinx release.
12/20/2001	1.1	Corrected differential pin pair designations.
11/18/2002	2.0	Added XC2S400E and XC2S600E and FG676. Removed L37 designation from FT256 pinouts. Minor corrections and clarifications to pinout definitions. Removed Preliminary designation.
02/14/2003	2.1	Added differential pairs table on page 57, fixed 3 P/N designation typos introduced in v2.0. Clarified that XC2S50E has two VREF pins per bank.
06/18/2008	2.3	Added Package Overview section. Updated all modules for continuous page, figure, and table numbering. Updated links. Synchronized all modules to v2.3.
08/09/2013	3.0	This product is obsolete/discontinued per XCN12026.